

Title (en)  
HOMOGENEOUS COOLING FOR WELDING PROCESSES, IN PARTICULAR WAAM

Title (de)  
HOMOGENE KÜHLUNG FÜR SCHWEISSVERFAHREN, INSBESONDERE WAAM

Title (fr)  
REFROIDISSEMENT HOMOGENE POUR PROCÉDÉ DE SOUDAGE, EN PARTICULIER PROCÉDÉ DE FABRICATION ADDITIVE ARC-FIL

Publication  
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Application  
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Priority  

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Abstract (en)  
[origin: WO2019192755A1] The invention relates to a welding process for producing a component (10) by depositing multiple layers (100) of a metal material in layers, said layers lying one on top of the other. In said process, the base (10a) of the component (10) is placed in a liquid coolant (6) such that the coolant contacts the base (6), and a surface (10b) of the base (6) lies above the coolant level (3). A first layer (100) of the material is deposited onto the surface (10b) by welding the material to the surface (10b), and each subsequent layer (100) is deposited onto a temporary component surface (10bb) formed by the previously deposited layer (100) by welding the material to the temporary component surface (10bb), wherein the heat resulting from welding the material is absorbed by the coolant (6). The invention additionally relates to a device (1) for carrying out the method.

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